Standardized Information for Process/Product Change Notification (PCN)

		1. PCN	basic data			
1.1 Company	TAIWAN SEMICONDUCTOR	TAIWAN SEMICONDUCTOR CO., LTD				
1.2 PCN No.		QPCN15007				
1.3 Title of PCN		TSM1N80CW die attach & bond wire change				
1.4 Product Category		Semiconductor components				
1.5 Issue date		2015/04/25				
1.6 PCN revision history (optional)		1.7 Issue date of previous revision (optional) previous revision (optional)				

2. PCN Team							
2.1 Contact supplier							
2.1.1 Name	Jack Wei						
2.1.2 Phone	+886 2 8913 1588 ext. 2001	+886 2 8913 1588 ext. 2001					
2.1.3 Email	jack_wei@mail.ts.com.tw	jack_wei@mail.ts.com.tw					
2.2 Team supplier (optional)							
2.2.1 Name (optional)	2.2.2 Phone (optional)	2.2.3 Email (optional)					
Chris Lin	+886 2 8913 1588 ext. 2406	chris_lin@mail.ts.com.tw					
Owen Wang	+886 2 8913 1588 ext. 2201	owen@mail.ts.com.tw					

3. Changes						
	3.1 Category	3.2 Type of change				
Change #1	Process - Assembly	Die attach material				
Change #2	Process - Assembly	Change of bond wire material				
Change #3						
Change #4						
Change #5						

4. Description of change							
	Old		New				
Change #1	Soft-solder		Silver epoxy	/			
Change #2	Au wire		Cu wire				
Change #3							
Change #4							
Change #5							
4.6 Anticipated impact on form, fit, function, reliability or processability?	No						
4.7 Reference parts with customer number (optional)							
	E Bassan / wasting!	for all a					
5.1 Motivation	5. Reason / motivation Enhance production, capacity flo		ige				
5.2 Additional explanation (optional)		,					
	6. Marking of parts / tracea	bility of o	change				
6.1 Description							
	7. Timing / sche	dule					
7.1 Date of qualification results	2015/04/09	-duio					
7.2 Last order date (optional)							
7.3 Last delivery date (optional)							
7.4 Intended start of delivery	2015/05/01						
7.5 Qualification samples available?							
	2015/04/09						
7.6 Customer feedback required until	2015/06/01						
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	8. Qualification / va	lidation					
8.1 Description (e.g. qual. plan/report, AEC-Q)	JESD JESD						
8.2 Qualification report and qualification results	available (see attachement) issue date						
	9. Input to customer for risk as	ssessme	nt process				
			-				
10. Attachments (e.g. new datasheet, additional documentation, pictures, process flow, sample plan,)							

11. Affected parts									
11.1 Current					11.2 New (if applicable)				
11.1.1 Customer Part No.	11.1.2 Supplier Part Name	11.1.3 Supplier Part No. (optional)	11.1.4 Package Name	11.1.5 Part Description (optional)	11.1.6 Additional Part Information (optional)	11.2.2 Supplier Part Name	11.2.3 Supplier Part No. (optional)	11.2.4 Package Name	11.2.6 Additional Part Information (optional)